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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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PNZ108CL (PN108CL)

Silicon planar type

For optical control systems

■ Features

- High sensitivity: $I_L = 3.5 \text{ mA (min.)}$
- Narrow directivity characteristics for effective use of light input
- Fast response: $t_r = 5 \text{ } \mu\text{s (typ.)}$
- Signal mixing capability using base pin
- Small size (low in height) package

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-emitter voltage (Base open)	V_{CEO}	20	V
Collector-base voltage (Emitter open)	V_{CBO}	30	V
Emitter-collector voltage (Base open)	V_{ECO}	3	V
Emitter-base voltage (Collector open)	V_{EBO}	5	V
Collector current	I_C	20	mA
Collector power dissipation	P_C	100	mW
Operating ambient temperature	T_{opr}	-25 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +100	$^\circ\text{C}$

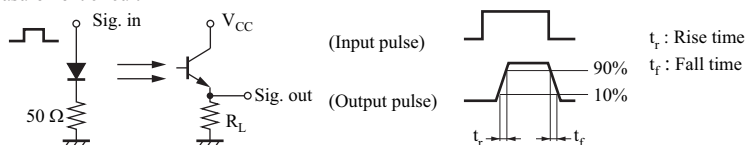
■ Electrical-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Photocurrent *1	I_L	$V_{CE} = 10 \text{ V}, L = 500 \text{ lx}$	3.5			mA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 10 \text{ V}$		0.05	2.0	μA
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_L = 1 \text{ mA}, L = 1000 \text{ lx}$		0.3	0.6	V
Peak sensitivity wavelength	λ_{PD}	$V_{CE} = 10 \text{ V}$		900		nm
Half-power angle	θ	The angle when the photocurrent is halved		80		$^\circ$
Rise time *2	t_r	$V_{CC} = 10 \text{ V}, I_L = 5 \text{ mA}, R_L = 100 \text{ } \Omega$		5		μs
Fall time *2	t_f			6		μs

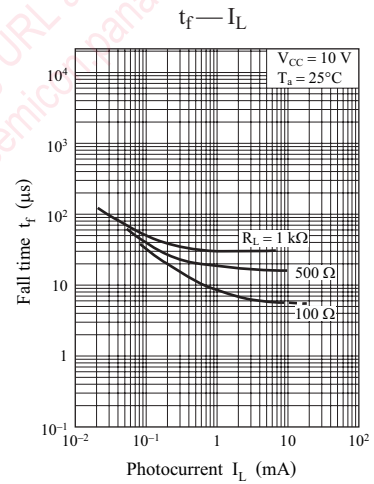
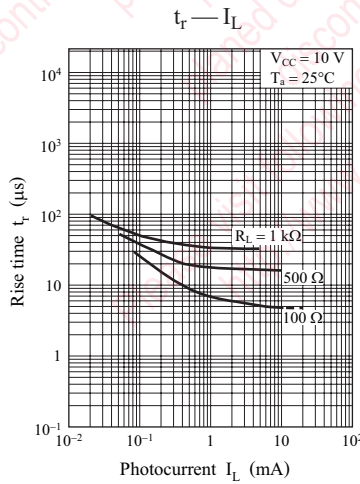
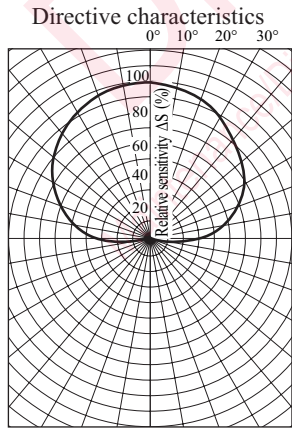
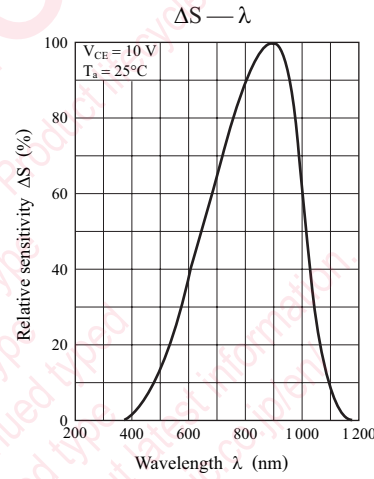
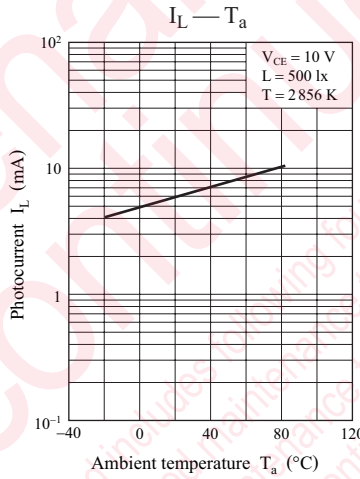
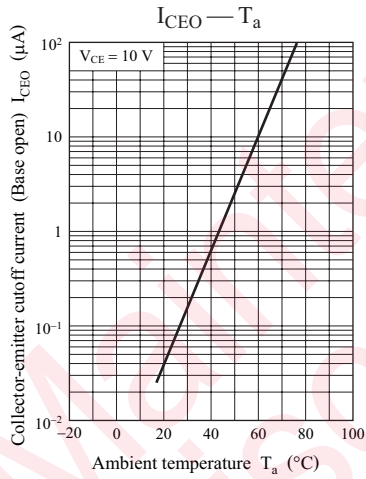
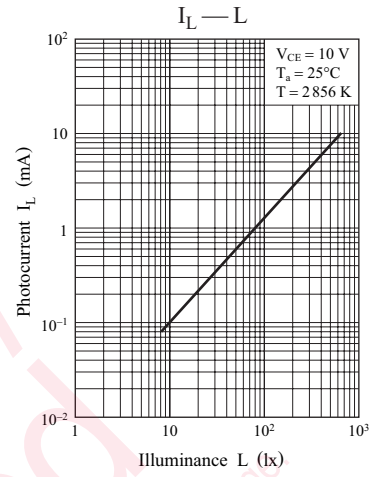
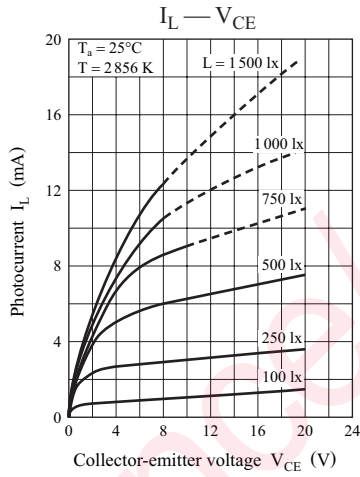
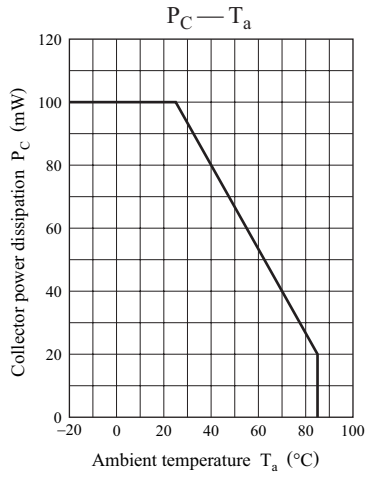
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. Spectral sensitivity characteristics: Sensitivity for wave length over 400 nm maximum sensitivity ratio is 100%.
3. This device is designed by disregarding radiation.
4. *1:Source: Tungsten lamp (color temperature 2 856K)

*2: Switching time measurement circuit

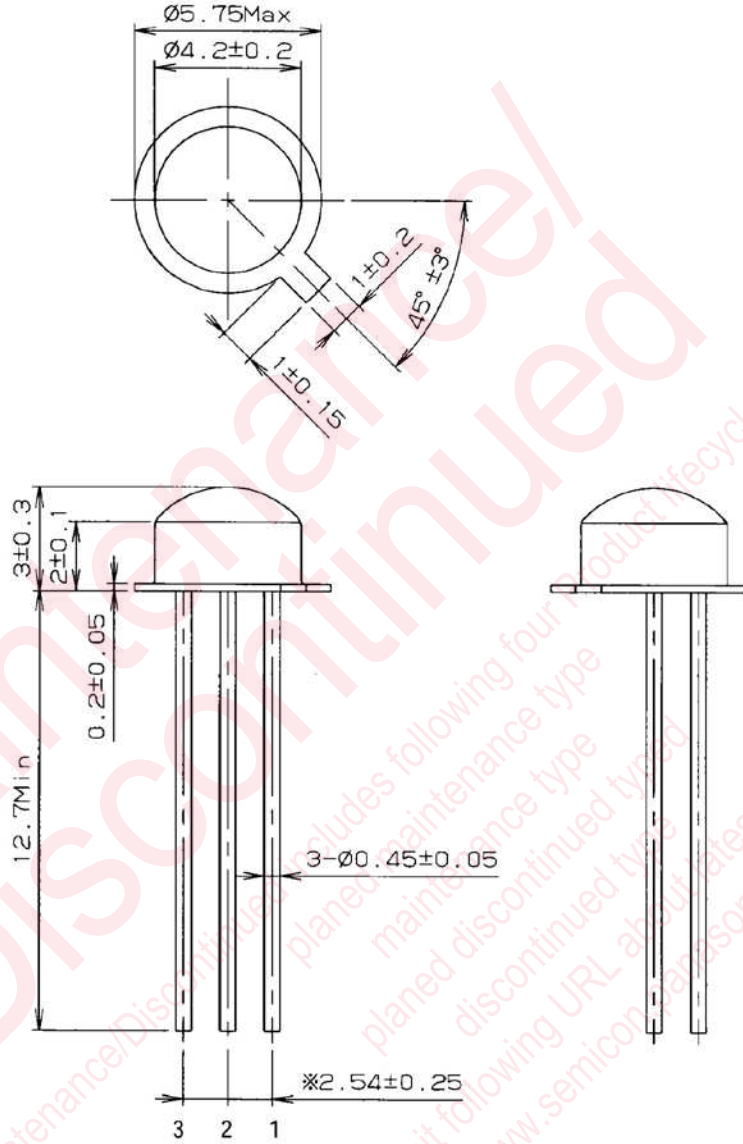


Note) The part number in the parenthesis shows conventional part number.



■ Package (Unit: mm)

MPDLTN3S0001



- Pin name
- 1: Emitter
- 2: Base
- 3: Collector

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